

MC74LVX259

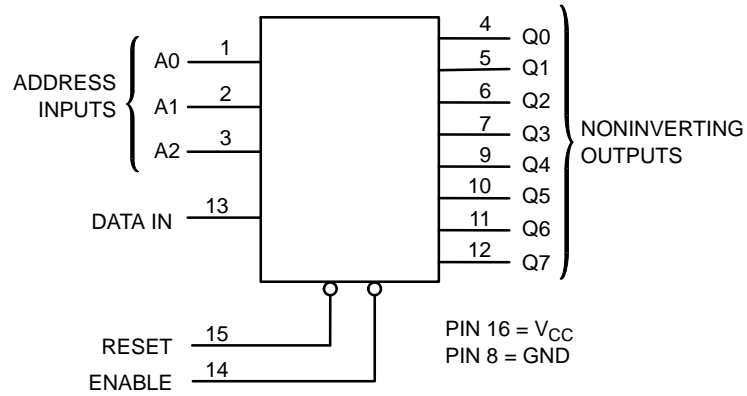


Figure 1. Logic Diagram

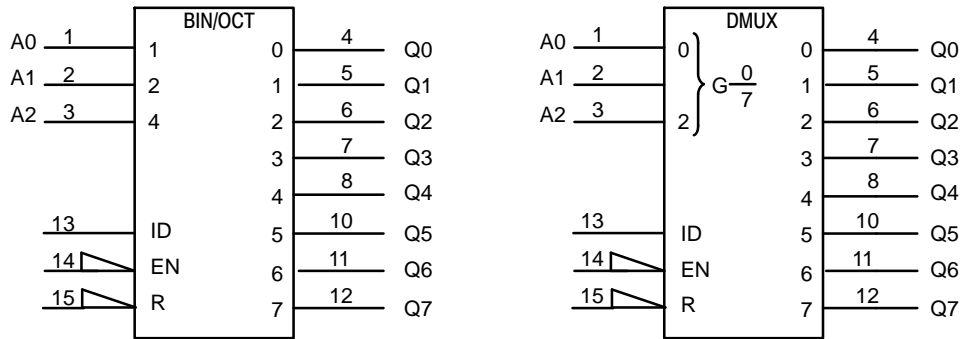


Figure 2. IEC Logic Symbol

MODE SELECTION TABLE

Enable	Reset	Mode
L	H	Addressable Latch
H	H	Memory
L	L	8-Line Demultiplexer
H	L	Reset

LATCH SELECTION TABLE

Address Inputs			Latch Addressed
C	B	A	
L	L	L	Q0
L	L	H	Q1
L	H	L	Q2
L	H	H	Q3
H	L	L	Q4
H	L	H	Q5
H	H	L	Q6
H	H	H	Q7

MC74LVX259

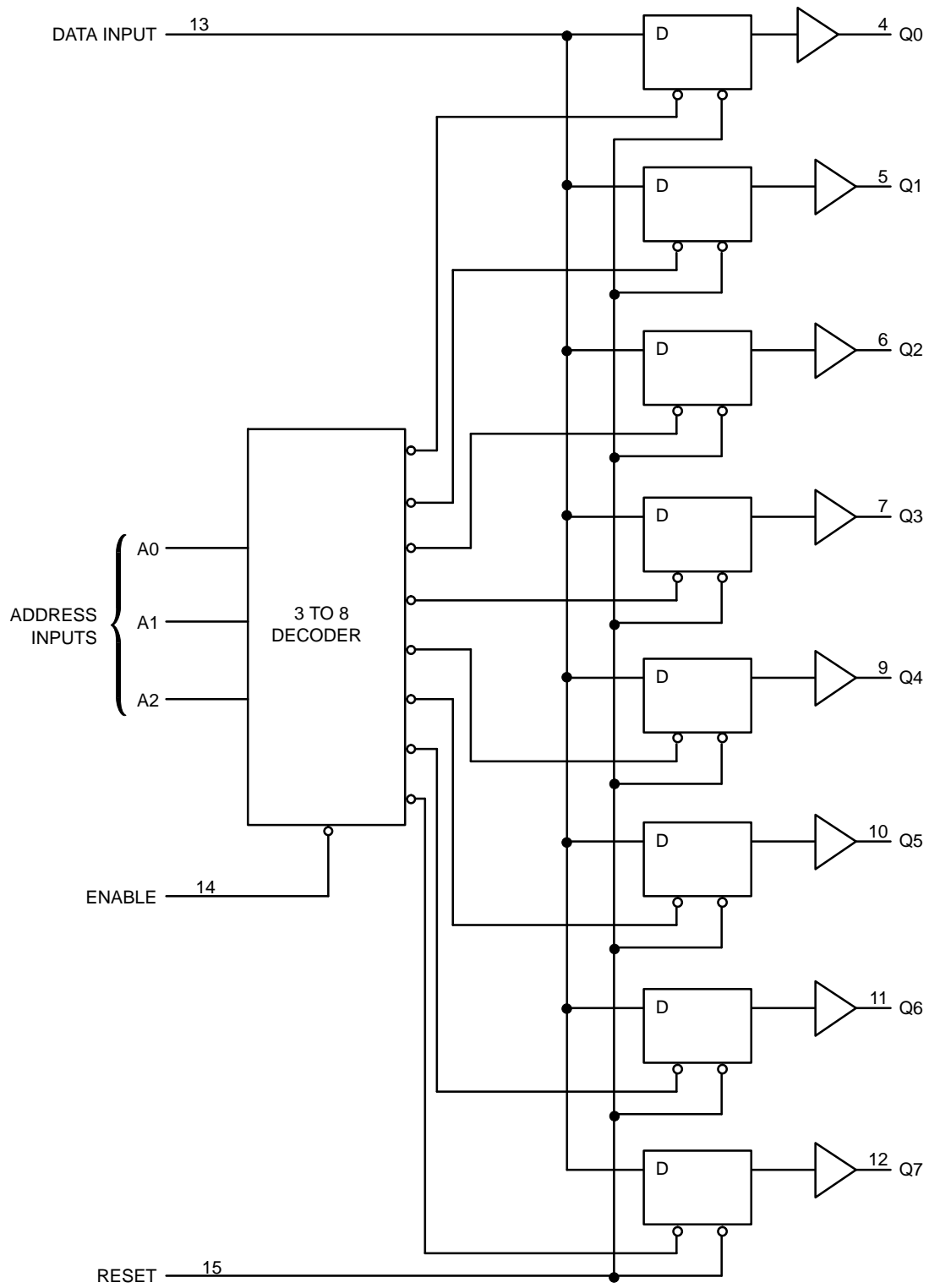


Figure 3. Expanded Logic Diagram

MC74LVX259

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	Positive DC Supply Voltage	-0.5 to +7.0	V
V _{IN}	Digital Input Voltage	-0.5 to +7.0	V
V _{OUT}	DC Output Voltage	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Diode Current	-20	mA
I _{OK}	Output Diode Current	±20	mA
I _{OUT}	DC Output Current, per Pin	±25	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±75	mA
P _D	Power Dissipation in Still Air	SOIC Package 200 TSSOP 180	mW
T _{STG}	Storage Temperature Range	-65 to +150	°C
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 1) > 2000 Machine Model (Note 2) > 200 Charged Device Model (Note 3) > 2000	V
I _{LATCHUP}	Latchup Performance	Above V _{CC} and Below GND at 125°C (Note 4)	±300 mA
θ _{JA}	Thermal Resistance, Junction-to-Ambient	SOIC Package 143 TSSOP 164	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Tested to EIA/JESD22-A114-A
2. Tested to EIA/JESD22-A115-A
3. Tested to JESD22-C101-A
4. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V _{CC}	DC Supply Voltage	2.0	3.6	V
V _{IN}	DC Input Voltage	0	5.5	V
V _{OUT}	DC Output Voltage	0	V _{CC}	V
T _A	Operating Temperature Range, all Package Types	-40	85	°C
t _r , t _f	Input Rise or Fall Time			ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

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DC CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25°C			-40°C ≤ T _A ≤ 85°C		Unit
				Min	Typ	Max	Min	Max	
V _{IH}	Minimum High-Level Input Voltage		2.0	0.75 V _{CC}	-	-	0.75 V _{CC}	-	V
			3.0	0.7 V _{CC}	-	-	0.7 V _{CC}	-	
			3.6	0.7 V _{CC}	-	-	0.7 V _{CC}	-	
V _{IL}	Maximum Low-Level Input Voltage		2.0	-	-	0.25 V _{CC}	-	0.25 V _{CC}	V
			3.0	-	-	0.3 V _{CC}	-	0.3 V _{CC}	
			3.6	-	-	0.3 V _{CC}	-	0.3 V _{CC}	
V _{OH}	High-Level Output Voltage	I _{OH} = -50 μA	2.0	1.9	2.0	-	1.9	-	V
		I _{OH} = -50 μA	3.0	2.9	3.0	-	2.9	-	
		I _{OH} = -4 mA	3.0	2.58	-	-	2.48	-	
V _{OL}	Low-Level Output Voltage	I _{OL} = 50 μA	2.0	-	0.0	0.1	-	0.1	V
		I _{OL} = 50 μA	3.0	-	0.0	0.1	-	0.1	
		I _{OL} = 4 mA	3.0	-	-	0.36	-	0.44	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 3.6	-	-	±0.1	-	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per package)	V _{IN} = V _{CC} or GND	3.6	1.0	1.0	2.0	-	-	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS Input t_r = t_f = 3.0 ns

Symbol	Parameter	Test Conditions	T _A = 25°C			-40°C ≤ T _A ≤ 85°C		Unit
			Min	Typ	Max	Min	Max	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Data to Output (Figures 4 and 8)	V _{CC} = 2.7 V C _L = 15pF	-	6.3	9.0	1.0	12.0	ns
		V _{CC} = 2.7 V C _L = 50pF	-	9.0	14.0	1.0	15.0	
		V _{CC} = 3.3 V ± 0.3 V C _L = 15pF	-	5.6	8.0	1.0	11.0	
		V _{CC} = 3.3 V ± 0.3 V C _L = 50pF	-	8.0	12.0	1.0	14.0	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Address Select to Output (Figures 5 and 8)	V _{CC} = 2.7 V C _L = 15pF	-	6.3	9.0	1.0	12.0	ns
		V _{CC} = 2.7 V C _L = 50pF	-	9.0	14.0	1.0	15.0	
		V _{CC} = 3.3 V ± 0.3 V C _L = 15pF	-	5.6	8.0	1.0	11.0	
		V _{CC} = 3.3 V ± 0.3 V C _L = 50pF	-	8.0	12.0	1.0	14.0	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Enable to Output (Figures 6 and 8)	V _{CC} = 2.7 V C _L = 15pF	-	6.3	9.0	1.0	12.0	ns
		V _{CC} = 2.7 V C _L = 50pF	-	9.0	14.0	1.0	15.0	
		V _{CC} = 3.3 V ± 0.3 V C _L = 15pF	-	5.6	9.0	1.0	11.0	
		V _{CC} = 3.3 V ± 0.3 V C _L = 50pF	-	8.0	12.0	1.0	14.0	
t _{PHL}	Maximum Propagation Delay, Reset to Output (Figures 6 and 8)	V _{CC} = 2.7 V C _L = 15pF	-	6.3	9.0	1.0	12.0	ns
		V _{CC} = 2.7 V C _L = 50pF	-	9.0	14.0	1.0	15.0	
		V _{CC} = 3.3 V ± 0.3 V C _L = 15pF	-	5.6	9.0	1.0	11.0	
		V _{CC} = 3.3 V ± 0.3 V C _L = 50pF	-	8.0	12.0	1.0	14.0	
C _{IN}	Maximum Input Capacitance		-	6	10	-	10	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	Typical @ 25°C, V_{CC} = 3.3 V						pF
		30						

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

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TIMING REQUIREMENTS Input $t_r = t_f = 3.0$ ns

Symbol	Parameter	Test Conditions	$T_A = 25^\circ\text{C}$			$T_A \leq 85^\circ\text{C}$		Unit
			Min	Typ	Max	Min	Max	
t_w	Minimum Pulse Width, Reset or Enable (Figure 7)	$V_{CC} = 2.7\text{ V}$	4.5	-	-	5.0	-	ns
		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	4.5	-	-	5.0	-	
t_{su}	Minimum Setup Time, Address or Data to Enable (Figure 7)	$V_{CC} = 2.7\text{ V}$	4.0	-	-	4.0	-	ns
		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	3.0	-	-	3.0	-	
t_h	Minimum Hold Time, Enable to Address or Data (Figure 6 or 7)	$V_{CC} = 2.7\text{ V}$	2.0	-	-	2.0	-	ns
		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	2.0	-	-	2.0	-	
t_r, t_f	Maximum Input, Rise and Fall Times (Figure 4)	$V_{CC} = 2.7\text{ V}$	-	-	400	-	300	ns
		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	-	-	300	-	300	

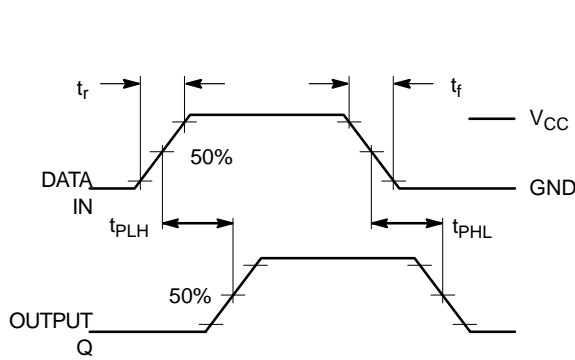


Figure 4. Switching Waveform

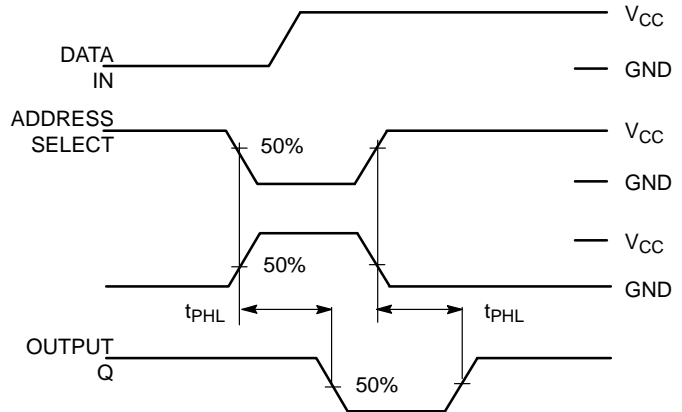


Figure 5. Switching Waveform

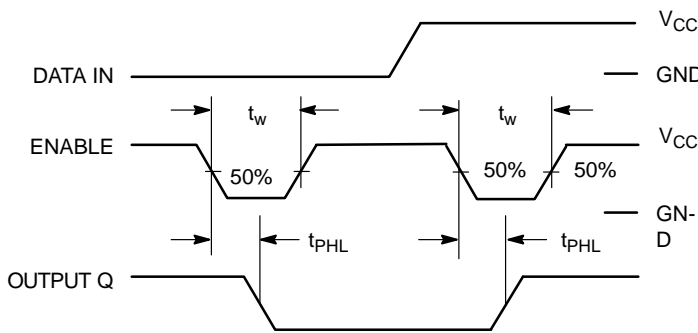


Figure 6. Switching Waveform

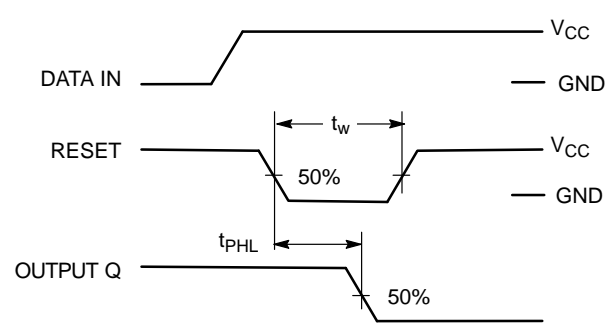


Figure 7. Switching Waveform

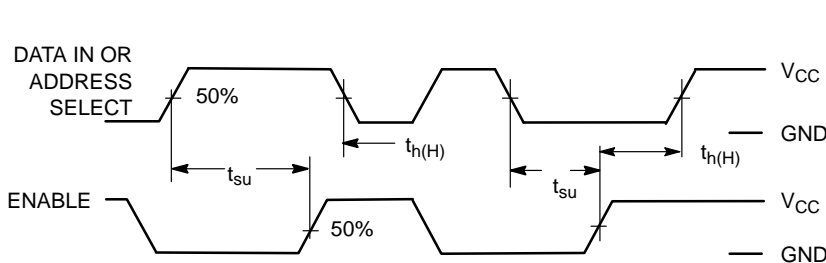
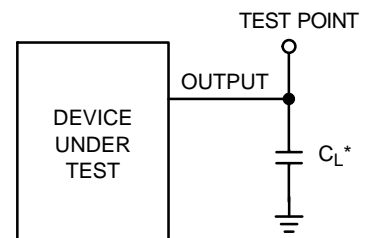


Figure 8. Switching Waveform



*Includes all probe and jig capacitance

Figure 9. Test Circuit

MC74LVX259

ORDERING INFORMATION

Device	Package	Shipping†
MC74LVX259DG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74LVX259DR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74LVX259DTG	TSSOP-16 (Pb-Free)	96 Units / Rail
MC74LVX259DTR2G	TSSOP-16 (Pb-Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

EMBOSSED CARRIER DIMENSIONS (See Notes 6 and 7)

Tape Size	B ₁ Max	D	D ₁	E	F	K	P	P ₀	P ₂	R	T	W
8 mm	4.35 mm (0.179")	1.5 mm + 0.1 -0.0 (0.059" +0.004 -0.0)	1.0 mm Min (0.179")	1.75 mm ±0.1 (0.069 ±0.004")	3.5 mm ±0.5 (1.38 ±0.002")	2.4 mm Max (0.094")	4.0 mm ±0.10 (0.157 ±0.004")	4.0 mm ±0.1 (0.157 ±0.004")	2.0 mm ±0.1 (0.079 ±0.004")	25 mm (0.98")	0.6 mm (0.024)	8.3 mm (0.327)
12 mm	8.2 mm (0.323")		1.5 mm Min (0.060)		5.5 mm ±0.5 (0.217 ±0.002")	6.4 mm Max (0.252")	4.0 mm ±0.10 (0.157 ±0.004") 8.0 mm ±0.10 (0.315 ±0.004")			30 mm (1.18")		12.0 mm ±0.3 (0.470 ±0.012")
16 mm	12.1 mm (0.476")				7.5 mm ±0.10 (0.295 ±0.004")	7.9 mm Max (0.311")	4.0 mm ±0.10 (0.157 ±0.004") 8.0 mm ±0.10 (0.315 ±0.004") 12.0 mm ±0.10 (0.472 ±0.004")					16.3 mm (0.642)
24 mm	20.1 mm (0.791")				11.5 mm ±0.10 (0.453 ±0.004")	11.9 mm Max (0.468")	16.0 mm ±0.10 (0.63 ±0.004")					24.3 mm (0.957)

6. Metric Dimensions Govern—English are in parentheses for reference only.

7. A₀, B₀, and K₀ are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1

SOIC-16 CASE 751B-05 ISSUE K

DATE 29 DEC 2006



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

- | | | | |
|--|--|--|--|
| <p>STYLE 1:</p> <p>PIN 1. COLLECTOR</p> <p>2. BASE</p> <p>3. EMITTER</p> <p>4. NO CONNECTION</p> <p>5. EMITTER</p> <p>6. BASE</p> <p>7. COLLECTOR</p> <p>8. COLLECTOR</p> <p>9. BASE</p> <p>10. EMITTER</p> <p>11. NO CONNECTION</p> <p>12. EMITTER</p> <p>13. BASE</p> <p>14. COLLECTOR</p> <p>15. EMITTER</p> <p>16. COLLECTOR</p> | <p>STYLE 2:</p> <p>PIN 1. CATHODE</p> <p>2. ANODE</p> <p>3. NO CONNECTION</p> <p>4. CATHODE</p> <p>5. CATHODE</p> <p>6. NO CONNECTION</p> <p>7. ANODE</p> <p>8. CATHODE</p> <p>9. CATHODE</p> <p>10. ANODE</p> <p>11. NO CONNECTION</p> <p>12. CATHODE</p> <p>13. CATHODE</p> <p>14. NO CONNECTION</p> <p>15. ANODE</p> <p>16. CATHODE</p> | <p>STYLE 3:</p> <p>PIN 1. COLLECTOR, DYE #1</p> <p>2. BASE, #1</p> <p>3. EMITTER, #1</p> <p>4. COLLECTOR, #1</p> <p>5. COLLECTOR, #2</p> <p>6. BASE, #2</p> <p>7. EMITTER, #2</p> <p>8. COLLECTOR, #2</p> <p>9. COLLECTOR, #3</p> <p>10. BASE, #3</p> <p>11. EMITTER, #3</p> <p>12. COLLECTOR, #3</p> <p>13. COLLECTOR, #4</p> <p>14. BASE, #4</p> <p>15. EMITTER, #4</p> <p>16. COLLECTOR, #4</p> | <p>STYLE 4:</p> <p>PIN 1. COLLECTOR, DYE #1</p> <p>2. COLLECTOR, #1</p> <p>3. COLLECTOR, #2</p> <p>4. COLLECTOR, #2</p> <p>5. COLLECTOR, #3</p> <p>6. COLLECTOR, #3</p> <p>7. COLLECTOR, #4</p> <p>8. COLLECTOR, #4</p> <p>9. BASE, #4</p> <p>10. EMITTER, #4</p> <p>11. BASE, #3</p> <p>12. EMITTER, #3</p> <p>13. BASE, #2</p> <p>14. EMITTER, #2</p> <p>15. BASE, #1</p> <p>16. EMITTER, #1</p> |
| <p>STYLE 5:</p> <p>PIN 1. DRAIN, DYE #1</p> <p>2. DRAIN, #1</p> <p>3. DRAIN, #2</p> <p>4. DRAIN, #2</p> <p>5. DRAIN, #3</p> <p>6. DRAIN, #3</p> <p>7. DRAIN, #4</p> <p>8. DRAIN, #4</p> <p>9. GATE, #4</p> <p>10. SOURCE, #4</p> <p>11. GATE, #3</p> <p>12. SOURCE, #3</p> <p>13. GATE, #2</p> <p>14. SOURCE, #2</p> <p>15. GATE, #1</p> <p>16. SOURCE, #1</p> | <p>STYLE 6:</p> <p>PIN 1. CATHODE</p> <p>2. CATHODE</p> <p>3. CATHODE</p> <p>4. CATHODE</p> <p>5. CATHODE</p> <p>6. CATHODE</p> <p>7. CATHODE</p> <p>8. CATHODE</p> <p>9. ANODE</p> <p>10. ANODE</p> <p>11. ANODE</p> <p>12. ANODE</p> <p>13. ANODE</p> <p>14. ANODE</p> <p>15. ANODE</p> <p>16. ANODE</p> | <p>STYLE 7:</p> <p>PIN 1. SOURCE N-CH</p> <p>2. COMMON DRAIN (OUTPUT)</p> <p>3. COMMON DRAIN (OUTPUT)</p> <p>4. GATE P-CH</p> <p>5. COMMON DRAIN (OUTPUT)</p> <p>6. COMMON DRAIN (OUTPUT)</p> <p>7. COMMON DRAIN (OUTPUT)</p> <p>8. SOURCE P-CH</p> <p>9. SOURCE P-CH</p> <p>10. COMMON DRAIN (OUTPUT)</p> <p>11. COMMON DRAIN (OUTPUT)</p> <p>12. COMMON DRAIN (OUTPUT)</p> <p>13. GATE N-CH</p> <p>14. COMMON DRAIN (OUTPUT)</p> <p>15. COMMON DRAIN (OUTPUT)</p> <p>16. SOURCE N-CH</p> | |

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



TSSOP-16
CASE 948F-01
ISSUE B

DATE 19 OCT 2006



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

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